Title (en)

METHOD FOR SELECTIVELY ELECTROPLATING A STRIP-SHAPED, METAL SUPPORT MATERIAL

Title (de)

VERFAHREN ZUR SELEKTIVEN GALVANISIERUNG EINES BANDARTIGEN, METALLISCHEN TRÄGERMATERIALS

Title (fr)

PROCEDE POUR LA GALVANISATION SELECTIVE D'UN MATERIAU SUPPORT METALLIQUE EN FORME DE BANDE

Publication

EP 1409772 B2 20080813 (DE)

Application

EP 02754718 A 20020620

Priority

- DE 10135349 A 20010720
- EP 0206824 W 20020620

Abstract (en)

[origin: US2004206629A1] A method for the continuous selective electroplating of a metallic substrate material (10) and more particularly of a substrate material band having prestamped contact elements, comprises the following steps: a) the substrate material (10) is coated in an electrophoretic coating means (14) with an electrophoretic coating composition selective with at least one composition strip, b) the at least one composition strip is removed at those parts by means of a laser (40), which are to be electroplated, c) in an electroplating process a metal layer is applied to the areas (42) deprived of composition in at least one composition strip using selective electroplating and d) the at least one composition strip is then removed.

IPC 8 full level

C25D 5/02 (2006.01); **C25D 7/06** (2006.01); **C25D 13/22** (2006.01)

CPC (source: EP US)

C25D 5/022 (2013.01 - EP US); **C25D 13/22** (2013.01 - EP US); Y10S 205/917 (2013.01 - EP US)

Citation (opposition)

Opponent :

- DE 68910864 T2 19940601 - WHITAKER CORP [US]
- EP 0337658 A1 19891018 - AMP INC [US]
- EP 0106977 A2 19840502 - IBM [US]
- DD 246575 A1 19870610 - SEGHERS A MIKROELEKTRONIK VEB [DD]
- DE 69403926 T2 19980102 - MECO EQUIP ENG [NL]

Cited by

CN102888632A

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

US 2004206629 A1 20041021; **US 6972082 B2 20051206**; AT E291110 T1 20050415; CN 1250777 C 20060412; CN 1533449 A 20040929; DE 10135349 A1 20030206; DE 50202493 D1 20050421; EP 1409772 A2 20040421; EP 1409772 B1 20050316; EP 1409772 B2 20080813; HK 1069607 A1 20050527; JP 2004536971 A 20041209; WO 03012175 A2 20030213; WO 03012175 A3 20031030

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